quality due to reflected light. In such a case, the polarizer may be adhered prior to the cut-out step, and the cut-out can be performed collectively by a laser and the like. Therefore, steps that adhere the polarizer can be simplified.

[0177] The display device **12** according to this example having such a structure also can suppress separation of the connection portion.

Second Embodiment

[0178] A method for manufacturing a display device according to a second embodiment of the invention is a method for manufacturing a display device including: a flexible first substrate **110**; a flexible second substrate **120** provided to face the first substrate **110**; a display part **180** having a display component **150** disposed between the first substrate **110** and the second substrate **120** to produce at least one of an optical characteristic change and a light emission; and a wiring substrate **130** connected to a connection pad **160** provided on at least one of the first substrate **110** and the second substrate **120**. The assembly of the first and second substrates **110** and **120** and the wiring substrate **130** is distinctive and therefore will be described.

[0179] FIG. **17** is a flowchart illustrating the method for manufacturing the display device according to the second embodiment of the invention.

[0180] In the method for manufacturing the display device according to this embodiment illustrated in FIG. **17**, first, the display component **150** is disposed in the display part **180** between the first and second substrates **110** and **120**, and the first substrate **110** and the second substrate **120** are disposed to face each other (step S**110**).

[0181] At least a portion of the wiring substrate **130** is inserted between the first substrate **110** and the second substrate **120** outside the display part **180**. The wiring substrate **130** is fixed to at least one of the first substrate **110** and the second substrate **120** (step S**120**).

[0182] In step S**110** recited above, the order of disposing the display component **150** in the display part **180** between the first and second substrates **110** and **120** and disposing the first substrate **110** and the second substrate **120** is arbitrary.

[0183] In other words, as described above, the bonding agent is provided in a prescribed configuration on the first and second substrates **110** and **120**, a prescribed amount of the liquid crystal is dropped on the inside of the bonding agent, and then the first substrate **110** and the second substrate **120** are adhered to each other in a vacuum to dispose the first substrate **110** and the second substrate **120** to face each other. At this time, the first substrate **110** and the second substrate **120** can be bonded. Alternatively, a bonding agent having a prescribed configuration may be provided on the first and second substrates **110** and **120**. Subsequently, the bonding agent may be cured to dispose the first and second substrates **110** and **120** facing each other. Then, the liquid crystal may be injected between the first and second substrates **110** and **120**.

[0184] An organic EL layer, i.e., the display component **150**, may be provided in, for example, the display part **180** of the first substrate **110** in the case where the display component **150** is, for example, an organic EL element. Then, the first substrate **110** and the second substrate **120** can be disposed facing each other.

[0185] Although the first and second substrates **110** and **120** are disposed facing each other in step S**110**, the first and second substrates **110** and **120** may be bonded at this time. The bond of the first and second substrates **110** and **120** may be performed in step S**120** or after step S**120**.

[0186] When inserting at least a portion of the wiring substrate **130** between the first substrate **110** and the second substrate **120** in step S**120**, at least a portion of the wiring substrate **130** may be inserted between the first and second substrates **110** and **120** in a state in which at least one of the first and second substrates **110** and **120** is lifted upward or downward using, for example, a vacuum chuck, etc., to increase the spacing between the first and second substrates **110** and **120**.

[0187] The wiring substrate **130** is fixed on at least one of the first substrate **110** and the second substrate **120**.

[0188] The method for manufacturing the display device recited above may use a method that makes multiple devices from a larger sheet as that illustrated in FIGS. **14**A to **14**D, or may use a method that makes a single device.

[0189] In the case where the method that makes multiple devices from a larger sheet is used, as described above, the first and second substrates **110** and **120** can be collectively cut. At this time, the end faces of the first and second substrates **110** and **120** can be cut in substantially the same plane.

[0190] Thus, the method for manufacturing the display device according to this embodiment may further include a step that collectively cuts at least a portion of the substrate forming the first substrate **110** (for example, the first sheet **110***f*) and the substrate forming the second substrate **120** (for example, the second sheet **120***f*) between step S**110** and step S**120**.

[0191] The step that collectively cuts at least a portion of the substrate forming the first substrate **110** and the substrate forming the second substrate **120** may be a step that cuts the substrate forming the first substrate **110** and the substrate forming the second substrate **120** such that the end faces of at least portions of the first substrate **110** and the second substrate **120** form substantially the same plane.

[0192] Such a method for manufacturing the display device according to this embodiment can suppress separation of the connection portion.

[0193] As described above, the method for manufacturing the display device according to this embodiment provides an advantage that a shock-absorbing material is unnecessary during thermal compression bonding of the wiring substrate **130** to at least one of the first and second substrates **110** and **120**.

[0194] Hereinabove, embodiments of the invention are described with reference to specific examples. However, the invention is not limited to these specific examples. For example, one skilled in the art may appropriately select specific configurations of components of the display device and the method for manufacturing the same from known art and similarly practice the invention. Such practice is included in the scope of the invention to the extent that similar effects thereto are obtained.

[0195] Further, any two or more components of the specific examples may be combined within the extent of technical feasibility; and are included in the scope of the invention to the extent that the purport of the invention is included.

[0196] Moreover, all display devices and methods for manufacturing the same that can be obtained by an appropriate design modification by one skilled in the art based on the display devices and the methods for manufacturing the same